



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

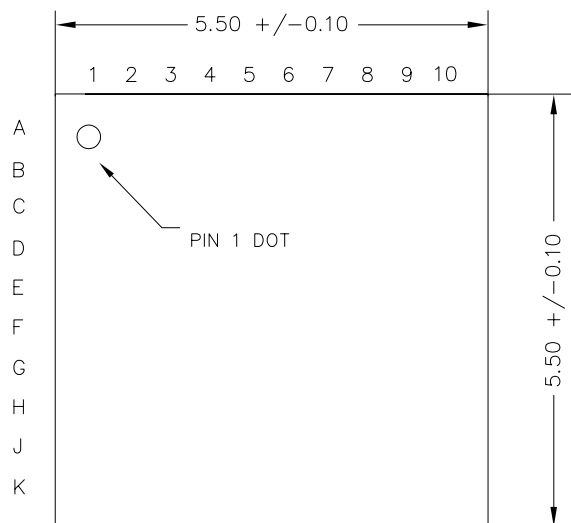
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

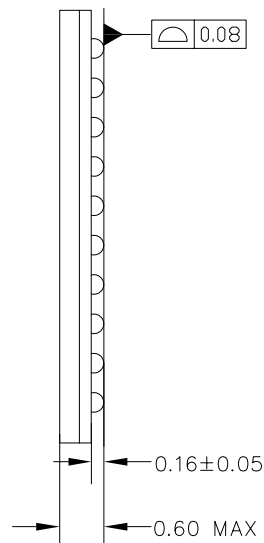
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

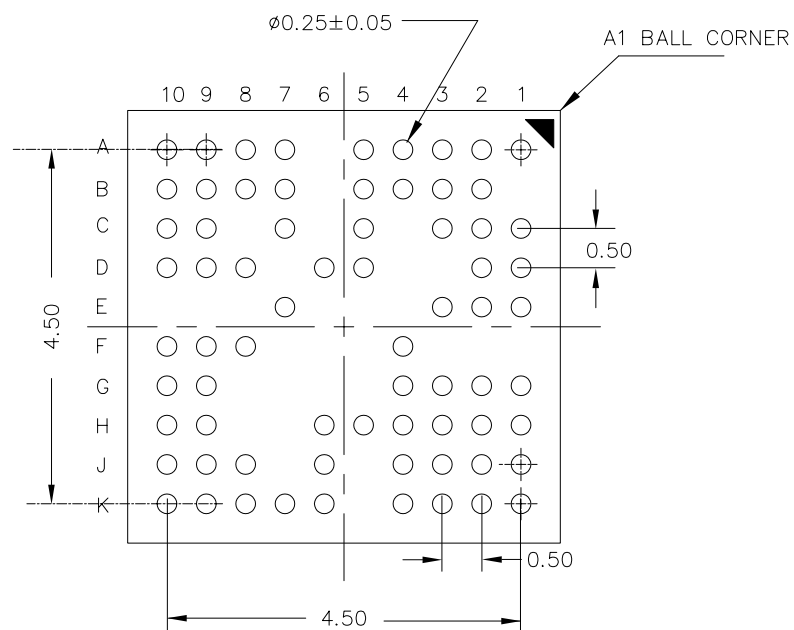
TOP VIEW



SIDE VIEW




BOTTOM VIEW



NOTES:

1. REFERENCE JEDEC # MO-280
2. ALL DIMENSIONS ARE IN MILLIMETERS

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 70L UFPGA 5.5X5.5X0.6MM BU70A	
SPEC NO. 001-83861	REV *A
SCALE: 1:1	SHEET 1 OF 2

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PACKAGE CODE(S)

BU70A

1

2

3

4

5

6

Rev.	ECN No.	Orig	Description of Change
**	3771528	JVP	NEW RELEASE
*A	3825708	JVP	CHANGE BALL MATRIX REQUIREMENT PER SYK-583

A

A

B


B

C

C

D

D

 CYPRESS Company Confidential	TITLE	
	PACKAGE OUTLINE, 70L UFBGA 5.5X5.5X0.6MM BU70A	
SPEC NO.	001-83861	REV *A
SCALE: 1:1	SHEET	2 of 2

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